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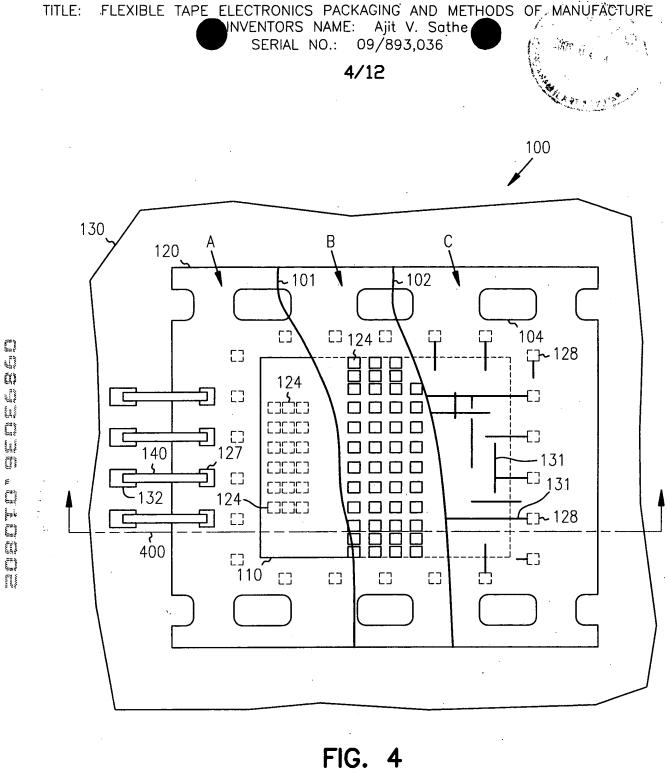
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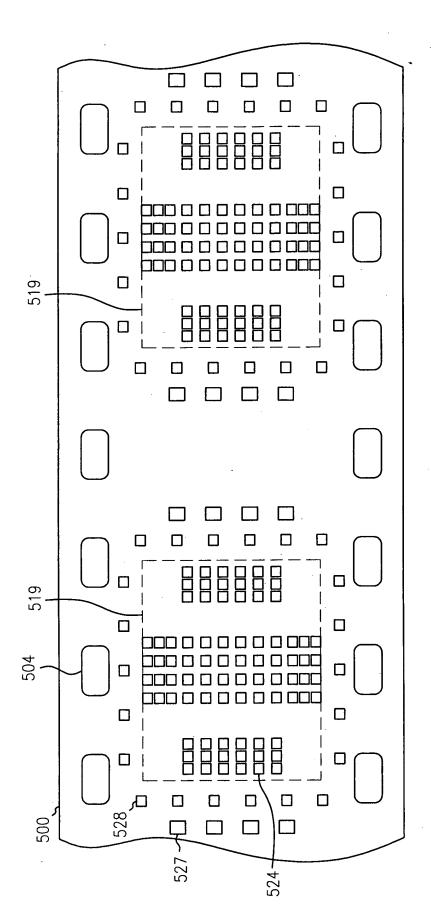
FIG. 1

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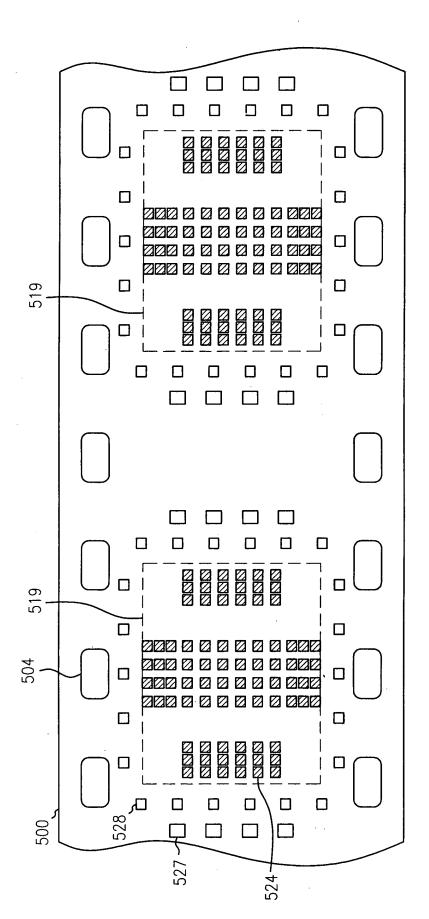


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FIG. 5



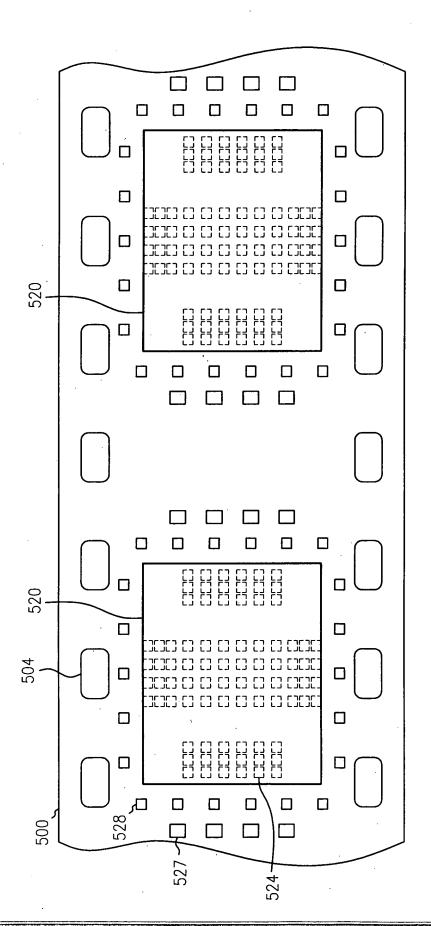
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FIG. 6

NVENTORS NAME: Ajit V. Sathe SERIAL NO.: 09/893,036

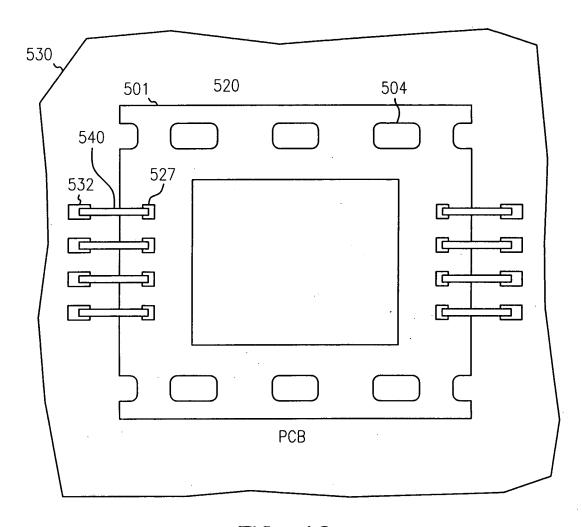
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FIG. 10

SERIAL NO.: 09/893,036

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METHOD OF MAKING A FLEXIBLE IC PACKAGE SUBSTRATE

602

METHOD OF MAKING A FLEXIBLE IC PACKAGE SUBSTRATE

- THE SUBSTRATE IS FORMED OF MATERIAL SUCH AS A POLYMERIC FILM, POLYIMIDE, POLYESTER, POLYPARABANIC ACID, EPOXY, FIBERGLASS, OR COMBINATION THEREOF
- THE SUBSTRATE HAS A CONDUCTOR REGION ADAPTED TO MOUNT AN IC
- THE SUBSTRATE CAN INCLUDE FROM 1 TO N LAYERS
- THE SUBSTRATE CAN COMPRISE SPROCKET HOLES OUTSIDE THE CONDUCTOR REGION

604

FORM A PLURALITY OF TRACES IN THE CONDUCTOR REGION

- THE TRACES CAN BE FORMED ON DIFFERENT LAYERS

606

FORM A PLURALITY OF LANDS COUPLED TO CERTAIN TRACES

- LANDS CAN BE FORMED ON OPPOSITE SURFACES OF THE SUBSTRATE
- LANDS CAN BE ARRANGED IN A BALL GRID ARRAY

608

FORM SOLDER BALLS ON THE PLURALITY OF LANDS

 THE SOLDER BALLS CAN BE FORMED ON DIFFERENT GROUPS OF THE LANDS, E.G. A FIRST SET TO COUPLE TO AN IC, A SECOND SET TO COUPLE TO A PCB

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FIG. 11

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700

METHOD OF MAKING AN ELECTRONIC ASSEMBLY

702

- THE SUBSTRATE IS FORMED OF MATERIAL SUCH AS A POLYMERIC FILM, POLYIMIDE, POLYESTER, POLYPARABANIC ACID, EPOXY, FIBERGLASS, OR COMBINATION THEREOF
- THE SUBSTRATE HAS A CONDUCTOR REGION
- THE CONDUCTOR REGION INCLUDES A PLURALITY OF TRACES AND A PLURALITY OF LANDS COUPLED TO CERTAIN TRACES
- THE SUBSTRATE CAN INCLUDE FROM 1 TO N LAYERS, EACH COMPRISING A PLURALITY OF TRACES IN THE CONDUCTOR REGION
- THE LANDS CAN BE FORMED ON DIFFERENT LAYERS
- THE SUBSTRATE CAN COMPRISE SPROCKET HOLES OUTSIDE THE CONDUCTOR REGION

704

FORM SOLDER BALLS ON A FIRST SET OF THE LANDS

- THE FIRST SET OF LANDS CAN BE A BALL GRID ARRAY

706

COUPLE PADS OF AN IC TO CORRESPONDING ONES OF THE FIRST SET OF LANDS

(12B

FIG. 12A

general course groups, groups were groups groups, groups groups, group

INVENTORS NAME: Ajit V. Sathe SERIAL NO.: 09/893,036

12/12

(12A)

708

MOUNT THE SUBSTRATE ON AN ADDITIONAL SUBSTRATE, E.G. A PCB

EMPLOY EITHER OR BOTH OF THE FOLLOWING:

- USE BGA BETWEEN SUBSTRATE AND PCB
 - FORM SOLDER BALLS ON A SECOND SET OF THE LANDS
 - COUPLE ONES OF THE SECOND SET OF LANDS TO CORRESPONDING TERMINALS ON THE PCB
- USE LEADS BETWEEN SUBSTRATE AND PCB
 - COUPLE LEADS, E.G. WIRES, BETWEEN CORRESPONDING ONES OF A THIRD SET OF LANDS AND ADDITIONAL TERMINALS OF THE PCB

END ~710

FIG. 12B